



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Michael B. Ball

**Serial No.:** 08/602,503

**Filed:** February 20, 1996

**For:** METHOD OF FABRICATING A  
MULTI-DIE SEMICONDUCTOR  
PACKAGE ASSEMBLY (as amended)

**Confirmation No.:** 4539

**Examiner:** Dilinh P. Nguyen

**Group Art Unit:** 2814

**Attorney Docket No.:** 2269-2718.4US  
(95-0837.04/US)

**\* Notice of Allowance Mailed:**

April 21, 2006

**NOTICE OF EXPRESS MAILING**

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Person making Deposit: Wendy Neff

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the specification** begin on page 3 of this paper;

**Amendments to the Abstract** appear on page 10 of this paper;

**A listing of the claims** begins on page 11 of this paper;

**Corrections to the drawings** are summarized on page 15 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

**Remarks** start at page 16 of this paper.